

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS75718KTTR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS75718KTTR	SN	Level-2-260C-1 YEAR	Ext-Mfg	KTT 5	8.42x10.16x4.58	2260.3

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000119	0.007349	73	0.000005	0
Precious Metals	Gold	7440-57-5	1.619153	99.992651	999927	0.071635	716
Sub-Total			1.619272	100	1000000	0.07164	716
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	1.692497	86.999993	870000	0.07488	749
Thermoplastics	Epoxy	85954-11-6	0.252902	13.000007	130000	0.011189	112
Sub-Total			1.945399	100	1000000	0.086069	861
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	1457.1798	99.8	998000	64.468702	644687
Other Nonferrous Metals and Alloys	Tin	7440-31-5	1.4601	0.1	1000	0.064598	646
Precious Metals	Silver	7440-22-4	1.4601	0.1	1000	0.064598	646
Sub-Total			1460.1	100	1000000	64.597898	645979
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.0124	100	1000000	0.000549	5
Sub-Total			0.0124	100	1000000	0.000549	5
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	670.841041	84.81	848100	29.67942	296794
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	41.131628	5.2	52000	1.81975	18197
Other Plastics and Rubber	Carbon Black	1333-86-4	1.661085	0.21	2100	0.07349	735
Thermoplastics	Epoxy	85954-11-6	77.359101	9.78	97800	3.422529	34225
Sub-Total			790.992855	100	1000000	34.995189	349952
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	5.620343	100	1000000	0.248656	2487
Sub-Total			5.620343	100	1000000	0.248656	2487
Total			2260.290269			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
 Created on: 06/12/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.